





OPTION 01 (.335 X .335)

SCALE: 20X

BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

BOND FINGERS	PIN No.	BOND FINGERS	PIN No.	BOND FINGERS	PIN No.
1	A6	27	L2	53	F10
2	B6	28	K2	54	E11
3	A5	29	L3	55	E10
4	B5	30	K3	56	D11
5	A4	31	L4	57	D10
6	B4	32	K4	58	C11
7	A3	33	L5	59	C10
8	B3	34	K5	60	B11
9	A2	35	L6	61	A10
10	B1	36	K6	62	B10
11	B2	37	L7	63	A9
12	C1	38	K7	64	B9
13	C2	39	L8	65	A8
14	D1	40	K8	66	B8
15	D2	41	L9	67	A7
16	E1	42	K9	68	B7
17	E2	43	L10		
18	F1	44	K11	S/R	NC
19	F2	45	K10		
20	G1	46	J11		
21	G2	47	J10		
22	H1	48	H11		
23	H2	49	H10		
24	J1	50	G11		
25	J2	51	G10		
26	K1	52	F11		

NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL EXPOSED METAL AND METALIZED AREAS TO BE GOLD PLATED 50 MICRONS MINIMUM OVER 50-350 MICRONS OF NICKEL.
2. SEAL RING TO BE ELECTRICALLY ISOLATED FROM ANY PINS.
3. INDEX MARK MAY BE ANY SHAPE WITHIN AREA INDICATED.
4. LEAD RESISTANCE (THE CLOSEST PIN):
 PADS 1, 10, 18, 27, 35, 44, 52 & 61 400 MILLIOHMS MAXIMUM.
 ALL OTHERS 600 MILLIOHMS MAXIMUM.